

Abstract

A chip package substrate having a soft circuit board has a multi-layer soft and hard composite PCB, a plurality of conducting components and a plurality of conducting holes. The conducting holes are formed in the multi-layer soft and hard composite PCB. The conducting components are electroplated on the inner edges of the conducting holes on the multi-layer soft and hard composite PCB. An image-sensing chip can thus be packaged on the chip package substrate with the soft circuit board used as external signal connection lines, thereby saving the manufacturing cost and increasing the yield thereof.

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